



Features

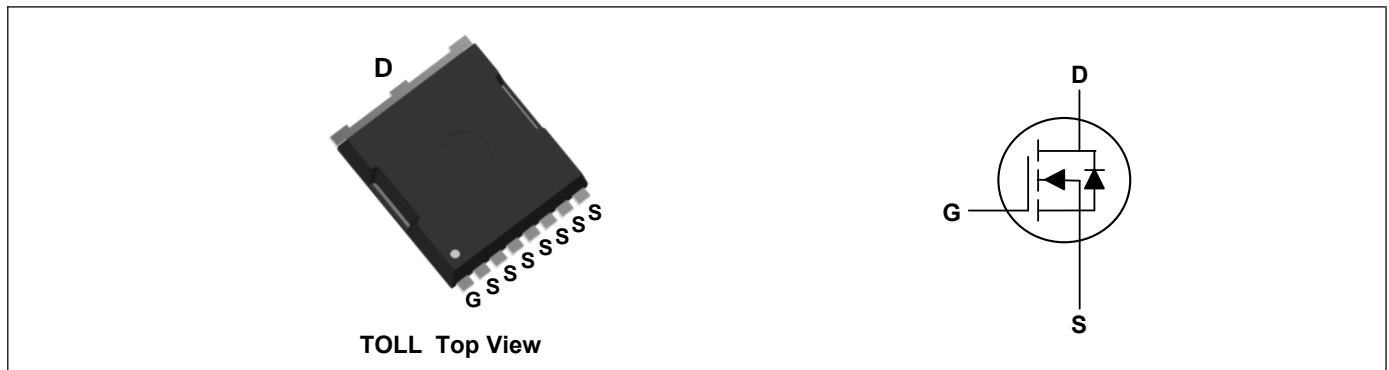
- Advanced Shield Gate Trench technology
- Super Low Gate Charge
- High-Speed Switching
- 100% EAS Guaranteed
- Green Device Available

Product Summary

V_{DS}	60	V
I_D	230	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	2.2	m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	2.9	m Ω

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D@T_C=25^\circ\text{C}$	230	A
Pulsed Drain Current ²	I_{DM}	640	A
Single Pulse Avalanche Energy ³	E_{AS}	1500	mJ
Total Power Dissipation ⁴	P_D	300	W
Storage Temperature Range	T_{STG}	-55 to 175	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	42	$^\circ\text{C/W}$
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	0.5	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	60	---	---	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =50A	---	1.8	2.2	mΩ
		V _{GS} =4.5V, I _D =30A	---	2.3	2.9	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250μA	1.0	---	2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J =25°C	---	---	1	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Total Gate Charge	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =50A	---	250	---	nC
Gate-Source Charge	Q _{gs}		---	58	---	
Gate-Drain Charge	Q _{gd}		---	30	---	
Turn-On Delay Time	T _{d(on)}	V _{DS} =30V, V _{GS} =10V, R _G =3.9Ω, I _D =50A	---	25	---	ns
Rise Time	T _r		---	113	---	
Turn-Off Delay Time	T _{d(off)}		---	198	---	
Fall Time	T _f		---	122	---	
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHz	---	14900	---	pF
Output Capacitance	C _{oss}		---	545	---	
Reverse Transfer Capacitance	C _{rss}		---	96	---	

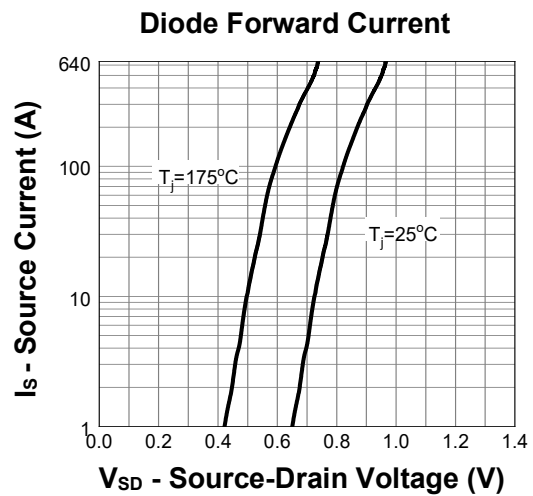
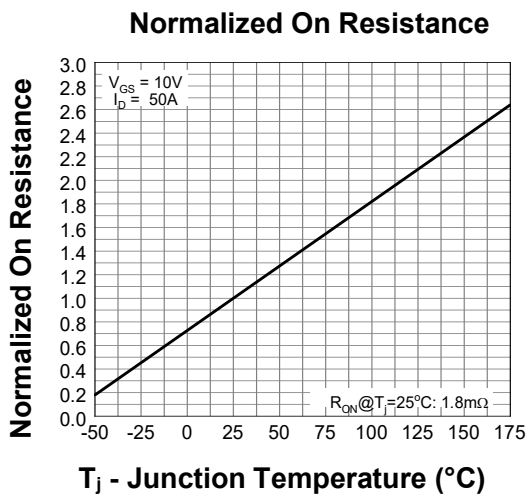
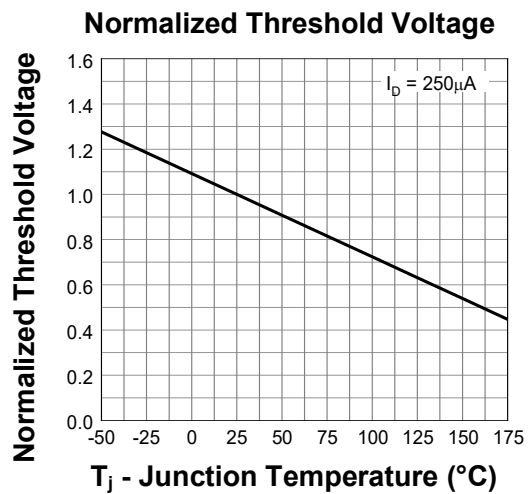
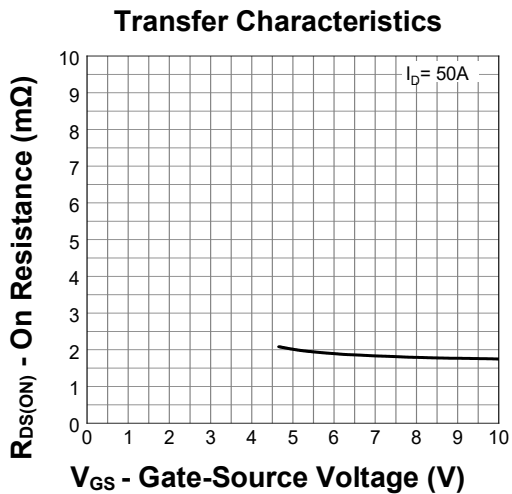
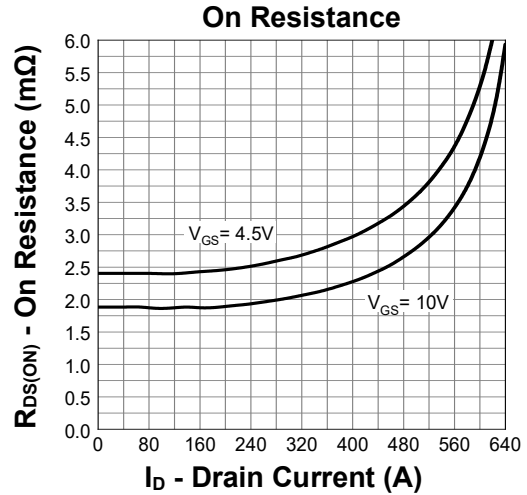
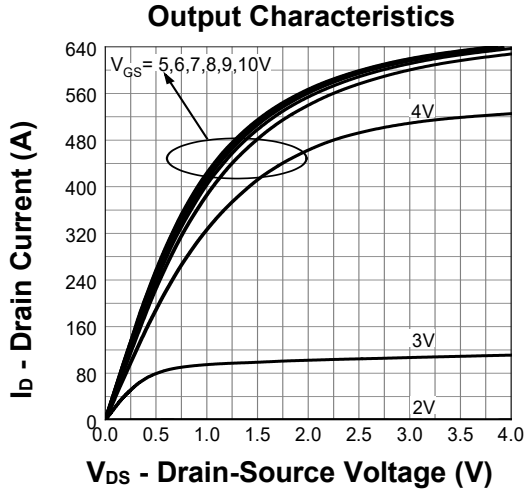
Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =50A, T _J =25°C	---	---	1.3	V
Reverse recovery time	t _{rr}	I _F =50A, diF/dt=100A/μs	---	22	---	ns
Reverse recovery charge	Q _{rr}		---	18	---	nC

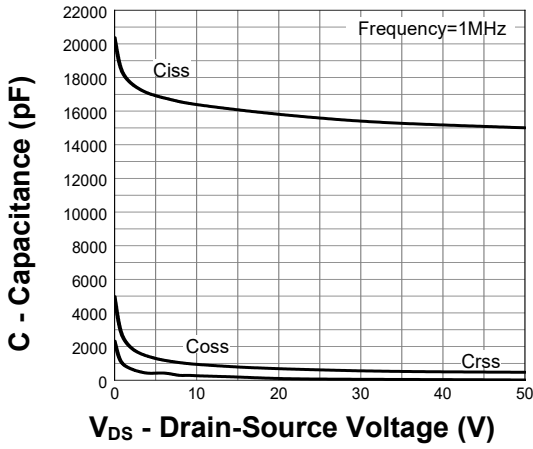
Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,L=0.5mH

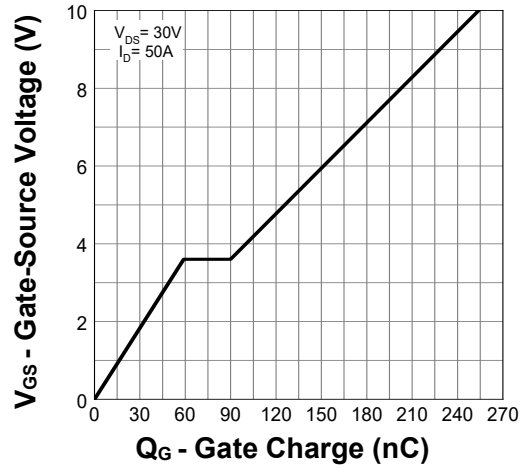
Typical Characteristics



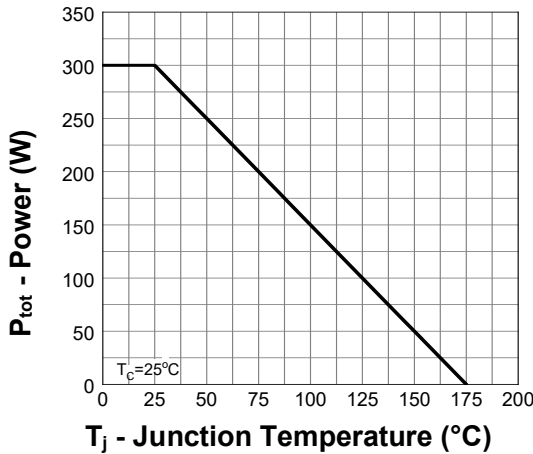
Capacitance



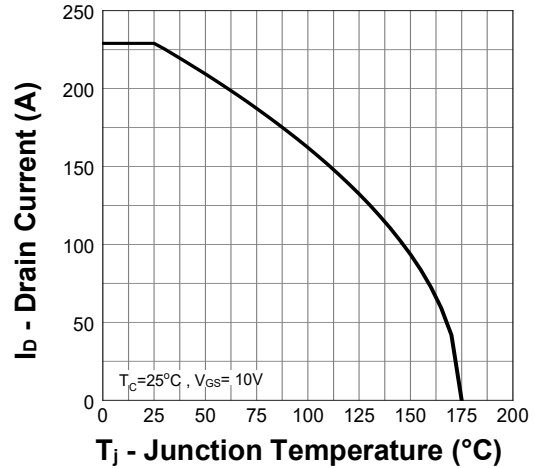
Gate Charge



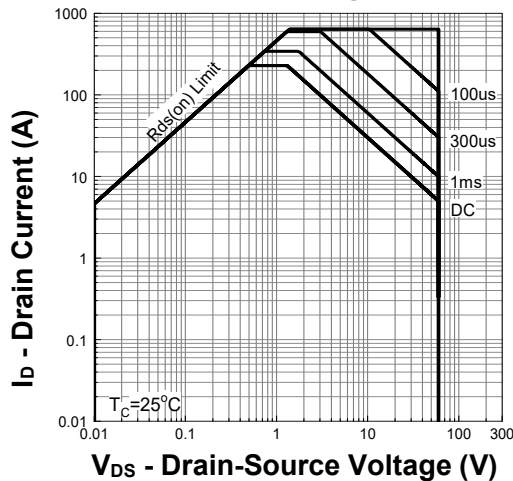
Power Capability



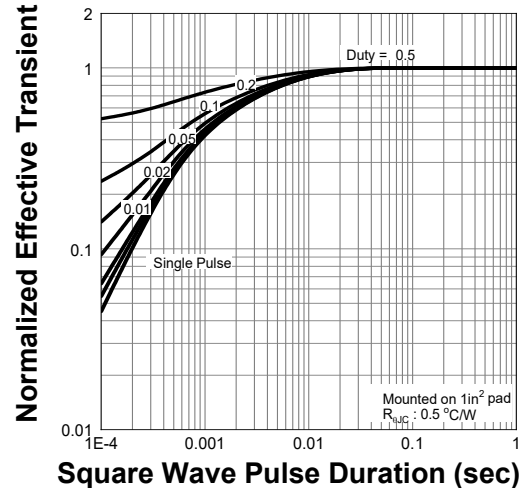
Current Capability



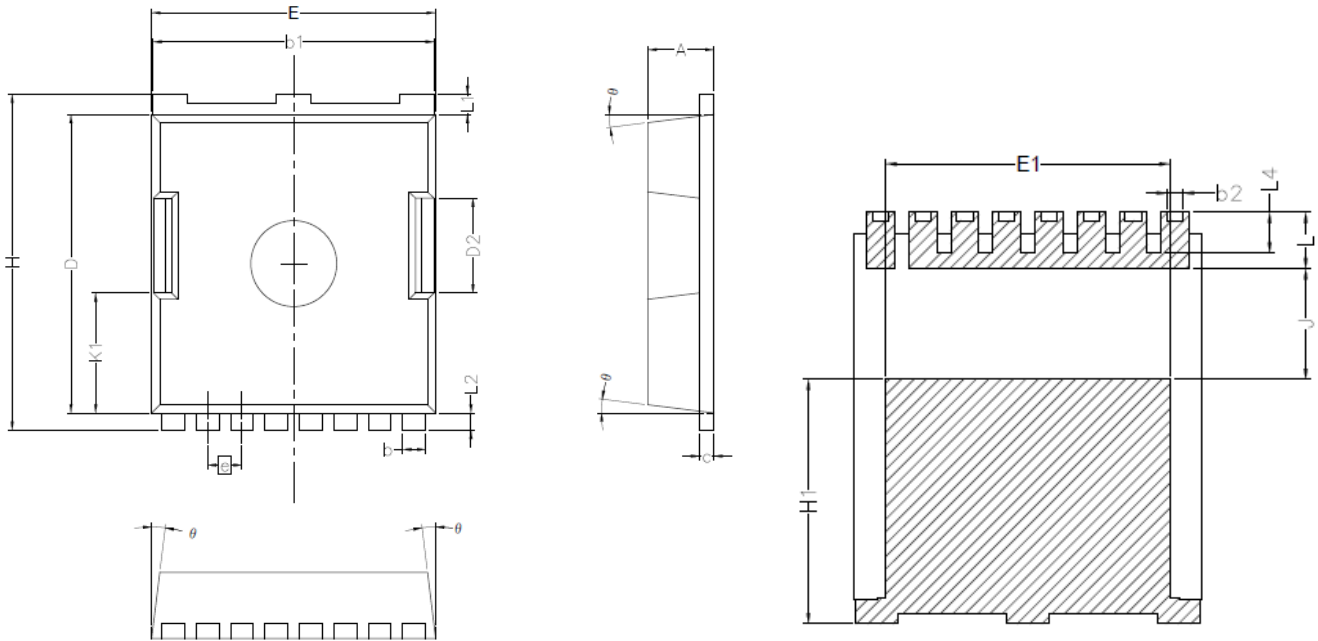
Safe Operating Area



Transient Thermal Impedance



TOLL Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.20	2.40
b	0.90	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°

Printing Information

ATC =====Brand

XXXXXXX =====Material Code

XXYY =====XX Representative Year
 YY Representative Weeks